



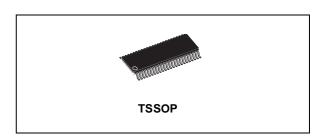
16 BIT LVTTL TO GTL/GTL + UNIVERSAL BUS TRANSCEIVERS WITH LIVE INSERTION

- HIGH SPEED GTL/GTL+ UNIVERSAL TRANSCEIVER:
 - t_{PD} = 4.6 ns (MAX.) A to B at V_{CC} = 3V
- COMBINES D-TYPE LATCHES AND D-TYPE FLIP-FLOPS FOR OPERATION IN TRANSPARENT, LATCHED, OR CLOCKED MODE
- OPERATING VOLTAGE RANGE: V_{CC}(OPR) = 3.0V to 3.6V
- SYMMETRICAL OUTPUT IMPEDANCE: |I_{OH}| = I_{OL}=24mA (MIN) at V_{CC} = 3V (A PORT)
- OUTPUT IMPEDANCE: I_{OL} = 100mA (MIN) at V_{CC} = 3V (B PORT)
- HIGH-IMPEDANCE STATE DURING POWER UP AND POWER DOWN up to Vcc=1.5V PERMITT LIVE INSERTION
- B-PORT PRECHARGED BY BIASVCC REDUCE NOISE ON THE LINE DURING LIVE INSERTION
- EDGE RATE-CONTROL INPUT CONFIGURES THE B-PORT OUTPUT RISE AND FALL TIMES
- BUS HOLD ON DATA INPUTS ELIMINATES THE NEED FOR EXTERNAL PULL-UP/ PULL-DOWN RESISTORS (A PORT)
- DISTRIBUTED VCC AND GND PIN CONFIGURATION MINIMIZES HIGH-SPEED SWITCHING NOISE IN PARALLEL COMUNICATIONS.
- PIN AND FUNCTION COMPATIBLE WITH 74 SERIES 1655

DESCRIPTION

The 74GTL1655 devices are 16-bit high-drive (100mA), low-output-impedance universal bus transceivers designed for backplane applications. The 74GTL1655 devices provide live-insertion capability for backplane applications by tolerating active signals on the data ports when the devices are powered off. In addition, a biasing pin preconditions the GTL/GTL+ port to minimize disruption to an active backplane.

The edge rate-control (V_{ERC}) input is provided so the rise and fall time of the B outputs can be configured to optimize for various backplane loading conditions. Data flow in each direction is controlled by output-enable (OEAB and OEBA),



ORDER CODES

PACKAGE	TUBE	T&R
TSSOP		74GTL1655TTR

PIN CONNECTION

		7
TOEAB [4] CLK
TOEBA [2 6	3 1LEAB
V _{cc} [3 6	2 1LEBA
1A1 [4 6	1 V _{EHC}
GND [5 6	o] GND
1A2 [6 5	9 D 1B1
1A3 [7 5	8] 1B2
GND [8 5	7] GND
1A4 [9 5	6] 1B3
GND [10 5	5 1B4
1A5 [11 5	4] 1B5
GND [12 5	3 GND
1A6 [13 5	2] 1B6
1A7 [14 5	1 187
V _{cc} [15 5	o V _{cc}
1A8 [9] 1B8
2A1 [17 4	8 2B1
GND [18 4	7] GND
2A2 [19 4	6] 2B2
2A3 [20 4	5] 2B3
GND [21 4	4] GND
2A4 [22 4	3] 2B4
2A5 [23 4	2 2 2B5
GND [24 4	1 V _{REF}
2A6 [o] 2B6
GND [26 3	gnd
2A7 [27 3	8 D 2B7
V _{cc} [28 3	7 D 288
2A8 [29 3	6 BIAS Vcc
GND [30 3	5 2LEAB
ZOEAB [31 3	4] 2LEBA
ZOEBA [32 3	3 DE
	CS03110	

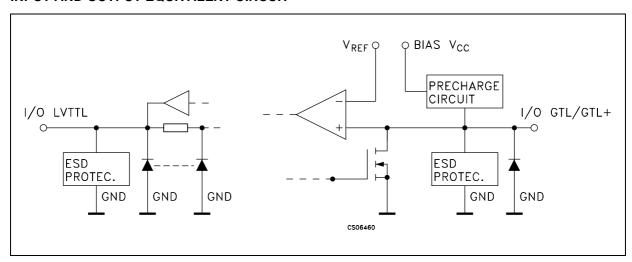
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latch-enable (LEAB and LEBA), and clock (CLK) inputs. For A-to-B data flow, the devices operate in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLK is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the low-to-high transition of CLK. When OEAB is low, the outputs are active. When OEAB is high, the outputs are in the high-impedance state. Data flow for B to A is similar to that of A to B, but uses OEBA, LEBA, and CLK. The output enable (OE) is used to disable both ports simultaneously.

Active bus-hold circuitry is provided on the A port to hold unused or floating data inputs at a valid logic level. When V_{CC} is between 0 and 1.5 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5V , \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

All input and output are equipped with protection circuits against static discharge, giving them 2KV ESD immunity and transient excess voltage.

INPUT AND OUTPUT EQUIVALENT CIRCUIT



PIN DESCRIPTION

PIN N°	SYMBOL	NAME AND FUNCTION
1, 2	1OEAB, 1OEBA	Output Enable Input
4, 6, 7, 9, 11, 13, 14, 16	1A1 to 1A8	Data Inputs/Outputs LVTTL
17, 19, 20, 22, 23, 25, 27, 29	2A1 to 2A8	Data Inputs/Outputs LVTTL
31, 32	2OEAB, 2OEBA	Output Enable Input
33	OE	Output Enable Input
34, 35	2LEBA, 2LEAB	Latch Enable
36	BIAS V _{CC}	Pre-Charge Supply Voltage
37, 38, 40, 42, 43, 45, 46, 48	2B8 to 2B1	Data Inputs/Outputs GTL/GTL+
41	V_{REF}	GTL Voltage Reference Input
49, 51, 52, 54, 55, 56, 58, 59	2A1 to 2A8	Data Inputs/Outputs GTL/GTL+
61	V_{ERC}	Edge Rate Control
62, 63	1LEBA, 1LEAB	Latch Enable
64	CLK	Clock Input (LOW to HIGH edge triggered)
5, 8, 10, 12, 18, 21, 24, 26, 30, 39, 44, 47, 53, 57, 60	GND	Ground (0V)
3, 15, 28, 50	V _{CC}	Positive Supply Voltage

FUNCTION TABLE (1)

	INPUTS				MODE
OEAB	LEAB	CLK	Α	В	MODE
Н	Х	X	X	Z	Isolation
L	Н	Х	L	L	Transparent
L	Н	X	Н	Н	Transparent
L	L		L	L	Registered
L	L		Н	Н	Registered
L	L	Н	Х	B0 ⁽²⁾	Previous State
L	L	L	Х	B0 ⁽³⁾	Previous State

1) A to B data flow is shown. B to A flow is similar, but uses OEBA, LEBA and CLK
2) Output level before the indicated steady-state input conditions were established, provided that CLK was high before LEAB went low
3) Output level before the indicated steady-state input conditions were established

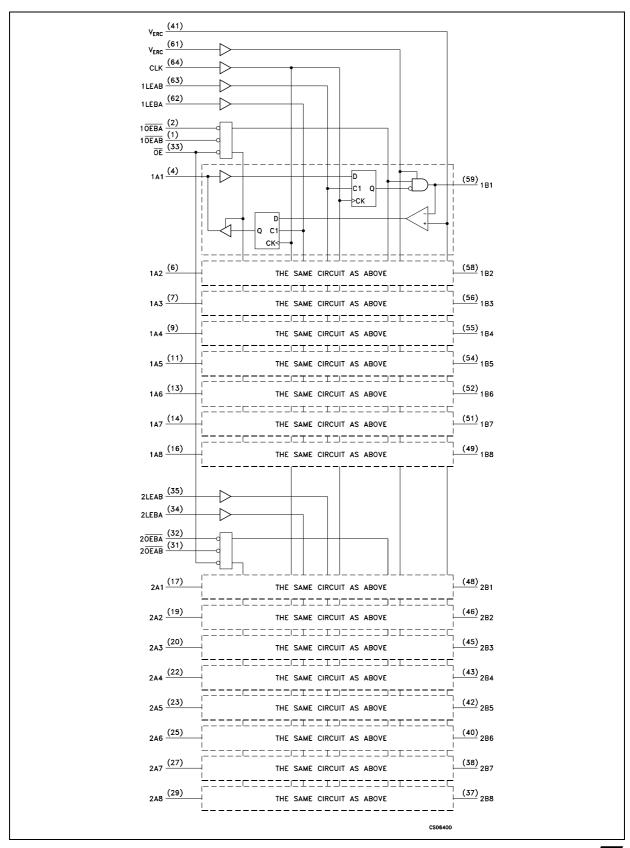
OUTPUT ENABLE TRUTH TABLE

	INPUTS	OUTPUTS		
ŌE	OEAB	OEBA	A PORT	B PORT
L	L	L	Active	Active
L	L	Н	Z	Active
L	Н	L	Active	Z
L	Н	Н	Z	Z
Н	X	Х	Z	Z

B-PORT EDGE RATE CONTROL (V_{ERC}) TRUTH TABLE

INPUT	OUTPUT B PORT EDGE RATE	
LOGIC LEVEL	NOMINAL VOLTAGE	OUT OF BY ON EDGE NATE
Н	V _{CC}	Slow
L	GND	Fast

LOGIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	Supply Voltage, Bias V _{CC}	-0.5 to +4.6	V
V _{IA}	DC Input Voltage A Side, Control Input	-0.5 to +4.6	V
V _{IB}	DC Input Voltage B Side, V _{ERC} , V _{REF}	-0.5 to +4.6	V
V _{OA}	DC Output Voltage A Side	-0.5 to +4.6	V
V _{OB}	DC Output Voltage B Side	-0.5 to +4.6	V
I _{IK}	DC Input Diode Current	- 50	mA
I _{OK}	DC Output Diode Current	- 50	mA
I _{OA}	DC Output Current A Side	± 48	mA
I _{OB}	DC Output Current B Side in the Low State	200	mA
T _{stg}	Storage Temperature	-65 to +150	°C
TL	Lead Temperature (10 sec)	300	°C

Absolute Maximum Rating are those value beyond which damage to the device may occur. Functional operation under these condition is not implied

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter			Unit		
Symbol	Parameter	Min.	Тур.	Max.	Unit	
V _{CC}	Supply Voltage		3.0	3.3	3.6	V
V _{TT}	Termination Voltage	GTL	1.14	1.2	1.26	V
		GTL+	1.35	1.5	1.65	V
V_{REF}	Supply Voltage	GTL	0.74	0.8	0.87	V
		GTL+	0.87	1	1.1	V
V _I	Input Voltage	B port	0		V _{TT}	V
		other	0		V _{CC}	
V _{IH}	High Level Input Voltage	B port	V _{REF} +0.05			V
		other	2			V
V _{IL}	Low Level Input Voltage	B port			V _{REF} -0.05	V
		other			0.8	٧
I _{IK}	Input Clamp Current				-18	mA
I _{OH}	High Level Output Current	A port			-24	mA
1	Low Level Output Current	A port			24	mΛ
l _{OL}		B port			100	mA
dt/dV _{CC}	Power -up ramp rate		200	•		μs/V
T _{op}	Operating Temperature		-40		85	°C

¹⁾ V_{TT} and R_{TT} can be adjusted to adapt backplane impedance if DC raccomanded I_{OL} ratings are not exceeded

²⁾ $\rm V_{REF}$ can be adjusted to optimaze noise margin (typ two-thirds $\rm V_{TT})$

DC SPECIFICATIONS

	Parameter		Te	est Condition			Unit	
Symbol			v _{cc}		-40 to 85 °C			;
			(Ÿ)		Min.	Тур.	Max.	1
V _{IK}	High Level Inpu	ıt Voltage	3				-1.2	V
V_{OHA}	High Level Our	out	3 to 3.6	I _O =-100μA	V _{CC} -0.2			
	Voltage A Port	•	3	I _O =-12mA	2.4			V
			3	I _O =-24mA	2.2			
V _{OLA}	Low Level Oup	ut Voltage	3 to 3.6	I _O =100μA			0.2	
	A Port	•	3	I _O =12mA			0.4	V
		•	3	I _O =24mA			0.55	1
V _{OLB}	Low Level Oup	ut Voltage	3	I _O =40mA			0.2	
	B Port	•	3	I _O =80mA			0.4	V
		•	3	I _O =100mA			0.5	1
lı	Input Current	Control	3.6	$V_I = V_{CC}$ or GND			±10	μА
		B Port	3.6	$V_I = V_{TT}$ or GND			±10	μА
I _{off}	Power Off Leak Current	age	0	V_I or $V_O = 0$ to 3.6V			±100	μΑ
	Bus Hold A Port Input Current		3	V _I = 0.8V	75		20	
			3	V _I = 2V	-75			μΑ
			3.6	$V_I = 0$ to V_{CC}			± 500	
I _{OZHB}	3-State Output Port	Current B	3.6	V _O = 1.5V			10	μА
I _{OZLB}	3-State Output Port	Current B	3.6	V _O = 0.4V			-10	μА
I _{OZ} (*)	3-State Output Port	Current A	3.6	$V_O = V_{CC}$ or GND			±10	μА
I _{OZPU}	3-State Output Port	Current A	0 to 1.5	$V_{\underline{O}} = 0.5 \text{ to } 3V$ $\overline{OE} = LOW$			±50	μА
I _{OZPD}	3-State Output Port	Current A	1.5 to 0	$V_{\underline{O}} = 0.5 \text{ to } 3V$ $\overline{OE} = LOW$			±50	μА
I _{CC}	Quiescent Sup Current	ply	3.6	$V_I = V_{CC}$ or GND $I_{O} = 0$		10	40	mA
Δl _{CC}	Δ Supply Curre B port	nt except	3.6	$V_{IN} = V_{CC}$ or GND One input $V_{CC} = 0.6V$			1	mA
C _I	Control Input Capacitance			$V_{IN} = V_{CC}$ or GND		3	5	pF
Co	Input Capacitar			$V_O = V_{CC}$ or GND		5	6	pF
	Input Capacitar	nce B Port		10 - 100 01 014D		6	8	Pi

^(*) For I/O ports, the parameter I_{OZ} includes the input leakage current

LIVE INSERTION SPECIFICATIONS

		Test Condition		Value			
Symbol	Parameter	V _{CC} (V)		-40 to 85 °C		;	Unit
				Min.	Тур.	Max.	
I _{CC} (Bias	Quiescent Bias Current	0 to 3.0	$V_{O(Bport)} = 0 \text{ to } 1.2V$			5	mA
Vcc)		3 to 3.6	$V_{I(Bias\ Vcc)} = 3 \text{ to } 3.6V$			10	μΑ
V _O	Output Voltage B Port	0	V _{I(Bias Vcc)} = 3.3V	1		1.2	V
Io	Output Current B Port	0	$V_{O(Bport)} = 0.4V$	-1			μΑ
			$V_{I(Bias\ Vcc)} = 3 \text{ to } 3.6V$				
		0 to 3.6	OE = 3.3V			100	μΑ
		0 to 1.5	OE = 0 to 3.3V			100	μΑ

AC ELECTRICAL CHARACTERISTICS for GTL

(V_{CC}=3.3 \pm 0.3V, V_{TT}=1.2V, V_{REF}=0.8V, V_{ERC}=V_{CC} or GND)

				Value		
Symbol	Parameter	ter Test Condition		-40 to 85 °C		
			Min.	Тур.	Max.	
f _{MAX}	Maximum Frequency		160			MHz
	A to B or B to A		160			IVITIZ
t _{PLH}	Propagation Delay Time	$V_{ERC}=V_{CC}$ R ₁ =12.5 Ω C _L =30pF	1.5		5.2	no
t _{PHL}	A to B		1.5		6.2	ns
t _{PLH}		$V_{ERC}=V_{CC}$ $R_{L}=12.5\Omega$ $C_{L}=30$ pF	1.5		5.5	
t _{PHL}	CK to B		1.5		5.8	ns
t _{PLH}	Propagation Delay Time	$V_{ERC}=V_{CC}$ $R_{L}=12.5\Omega$ $C_{L}=30pF$	1.5		5.8	
t _{PHL}	LEAB to B		1.5		6.4	ns
t _{EN}	Enable Delay Time OEAB or OE to B	$V_{ERC}=V_{CC}$ $R_{L}=12.5\Omega$ $C_{L}=30pF$	1.5		5.4	
t _{DIS}	Disable Delay Time OEAB or OE to B		1.5		6.2	ns
t _{PLH}	Propagation Delay Time		1.5		4.3	
t _{PHL}	A to B		1.5		4.6	ns
t _{PLH}	Propagation Delay Time	V_{ERC} =GND R _L =12.5 Ω C _L =30pF	1.5		4.3	
t _{PHL}	CK to B		1.5		4.9	ns
t _{PLH}		V_{ERC} =GND R _L =12.5 Ω C _L =30pF	1.5		4.9	
t _{PHL}	LEAB to B		1.5		4.8	ns
t _{EN}	Enable Delay Time OEAB or OE to B	V_{ERC} =GND R _L =12.5 Ω C _L =30pF	1.5		4.8	
t _{DIS}	Disable Delay Time OEAB or OE to B		1.5		4.2	ns
t _{PLH}	Propagation Delay Time	$R_L=500\Omega$ $C_L=50pF$	1.5		4.7	
t _{PHL}	B to A		1.5		4.8	ns
t _{PLH}		$R_L=500\Omega$ $C_L=50pF$	1.5		4	
t _{PHL}	CK to A		1.5		4	ns
t _{PLH}		$R_L=500\Omega$ $C_L=50pF$	1.5		4	
t _{PHL}	LEBA to A		1.5		3.7	ns

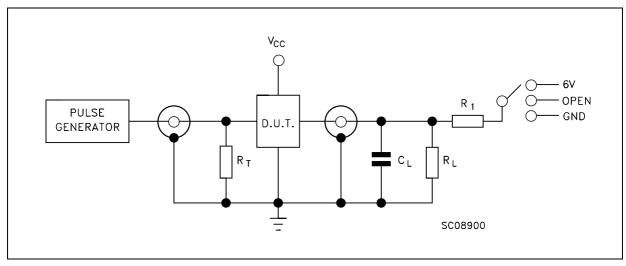
		Test Condition			Value			
Symbol	Parameter			Test Condition -40 to 85 °C			Unit	
				Min.	Тур.	Max.		
t _{EN}	Enable Delay Time OEBA or OE to A	R_L =500Ω R_1 =500Ω C_L =50pF		1		4.6		
t _{DIS}	<u>Disabl</u> e D <u>ela</u> y Time OEBA or OE to A			1		6.1	ns	
t _{SU}	Set-up Time	Data before clock	(2.7				
		Data before LE	Ck High	2.8			ns	
			Ck Low	2.6				
t _H	Hold Time	Data after clock		0.4			20	
		Data after LE Ck	High or LOW	0.9			ns	
t _W	Pulse duration	LE High		3				
		CK High or Low		3			ns	
Slew rate	Slew rate B output both	V _{ERC} =V _{CC}				1	ns/V	
	transition (0.6 to 1.3V)	V _{ERC} =GND				1	115/ V	
t _{sk}	Skew between drivers (in	Switching in the same direction				1	ns	
	the same package)	Switching in any direction				1		

AC ELECTRICAL CHARACTERISTICS for GTL+ (V_{CC}=3.3 \pm 0.3V, V_{TT}=1.5V, V_{REF}=1.0V, V_{ERC}=V_{CC} or GND)

				Unit			
Symbol	Parameter	Test Condition	-40 to 85 °C				
			Min.	Тур.	Max.]	
f _{MAX}	Maximum Frequency		160			MHz	
	B to A or A to B					IVITZ	
t _{PLH}		$V_{ERC} = V_{CC} R_L = 12.5\Omega C_L = 30pF$	1.5		5.1	ns	
t _{PHL}	A to B		1.5		6.5		
t _{PLH}		$V_{ERC}=V_{CC}$ R _L =12.5 Ω C _L =30pF	1.5		5.4	ns	
t _{PHL}	CK to B		1.5		6.2		
t _{PLH}	Propagation Delay Time	$V_{ERC}=V_{CC}$ $R_L=12.5\Omega$ $C_L=30$ pF	1.5		5.7	ns	
t _{PHL}	LEAB to B		1.5		6.7		
t _{EN}	Enable Delay Time OEAB or OE to B	$V_{ERC}=V_{CC}$ $R_{L}=12.5\Omega$ $C_{L}=30pF$	1.5		5.5		
t _{DIS}	Disable Delay Time OEAB or OE to B		1.5		5.8	ns	
t _{PLH}	Propagation Delay Time	V_{ERC} =GND R _L =12.5 Ω C _L =30pF	1.0		4.3		
t _{PHL}	A to B		1.0		4.9	ns	
t _{PLH}	Propagation Delay Time	V_{ERC} =GND R _L =12.5 Ω C _L =30pF	1.0		4.0		
t _{PHL}	CK to B		1.0		5.5	ns	
t _{PLH}	Propagation Delay Time	V_{ERC} =GND R _L =12.5 Ω C _L =30pF	1.0		4.0	ns	
t _{PHL}	LEAB to B		1.0		5.4		
t _{EN}	Enable Delay Time OEAB or OE to B	V_{ERC} =GND R_L =12.5 Ω C_L =30pF	1.0		5.1		
t _{DIS}	Disable Delay Time OEAB or OE to B		1.0		4.9	– ns	

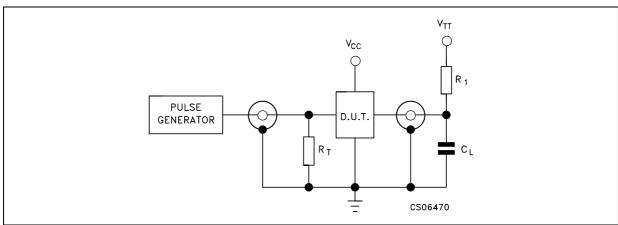
		Test Condition			Unit			
Symbol	Parameter			-40 to 85 °C				
				Min.	Тур.	Max.]	
t _{PLH}	Propagation Delay Time	me R_L =500 Ω C_L =50pF		1.5		4.8	ns	
t _{PHL}	B to A			1.5		4.7		
t _{PLH}		R_L =500 Ω C_L =50pF		1.5		4.4	ns	
t _{PHL}	CK to A			1.5		4.1		
t _{PLH}		$R_L=500\Omega$ $C_L=50p$	oF.	1.5		4	200	
t _{PHL}	LEBA to A			1.5		3.7	ns	
t _{EN}	Enable Delay Time OEBA or OE to A	R_L =500Ω R_1 =500Ω C_L =50pF		1		4.2	- ns	
t _{DIS}	Disable Delay Time OEBA or OE to A			1		6.1		
Slew rate	Slew rate B output both	$V_{ERC}=V_{CC}$ $R_{L}=12.5\Omega$ $C_{L}=30pF$				1	ns/V	
	transition (0.6 to 1.3V)	V_{ERC} =GND R_L =12.5 Ω C_L =30pF				1		
t _W	Pulse duration	LE High		3			nc	
		CK High or Low		3			ns	
t _{SU}	Set-up Time	Data before clock		2.7				
		Data before LE	Ck High	2.8			ns	
			Ck Low	2.6				
t _H	Hold Time	Data after clock		0.4			- ns	
		Data after LE Ck High or LOW		0.9				
t _{sk}	Skew between drivers (in	Switching in the same direction				1	ns	
	the same package)	Switching in any direction				1		

TEST CIRCUIT FOR "A" OUTPUTS



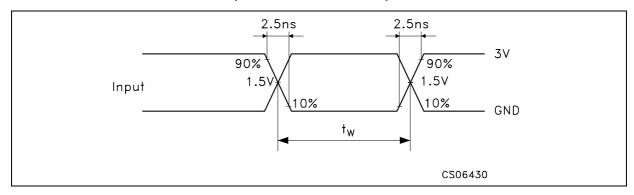
Test	Switch
t _{PLH} , t _{PHL}	Open
t _{PZL} , t _{PLZ}	6V
t _{PZH} , t _{PHZ}	GND
C_L = 50pF or equivalent (includes jig and probe capacitance) R_L = R_1 = 500Ω or equivalent R_T = Z_{OUT} of pulse generator (typically 50Ω) t_r = t_f <=2.5ns	

TEST CIRCUIT FOR "B" OUTPUTS

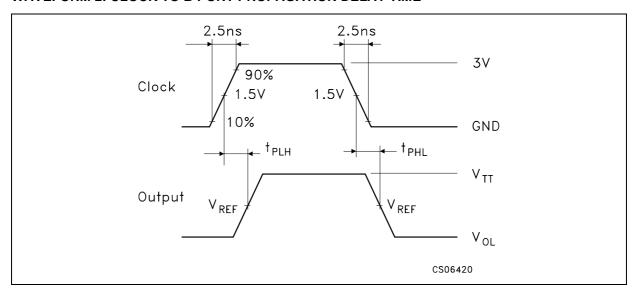


 $C_L=30 pF$ or equivalent (includes jig and probe capacitance) $R_L=R1=12.5\Omega$ or equivalent $R_T=Z_{OUT}$ of pulse generator (typically 50Ω) $t_{,}$ = t_{f} <=2.5ns

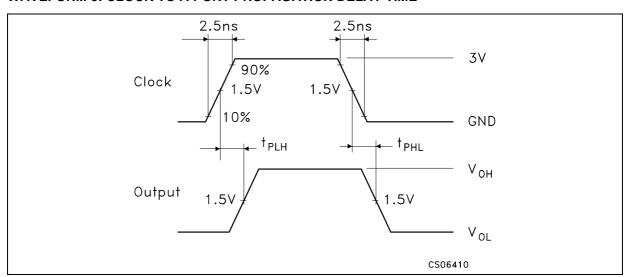
WAVEFORM 1: PULSE DURATION (A PORT, CONTROL PIN)



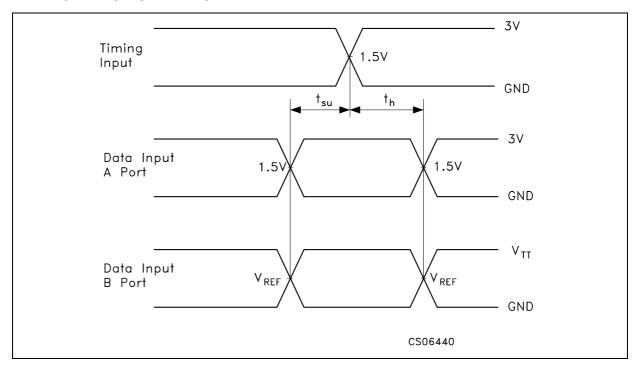
WAVEFORM 2: CLOCK TO B PORT PROPAGATION DELAY TIME



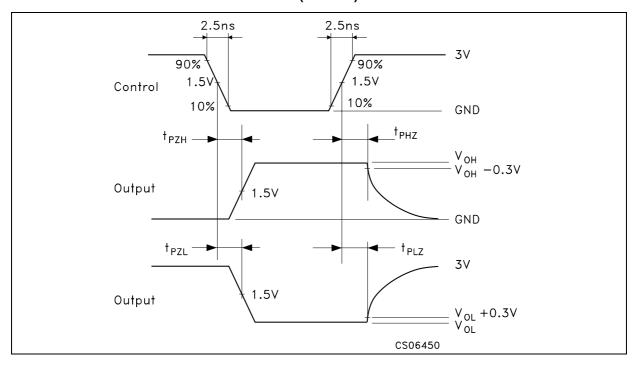
WAVEFORM 3: CLOCK TO A PORT PROPAGATION DELAY TIME



WAVEFORM 4: SETUP AND HOLD TIME

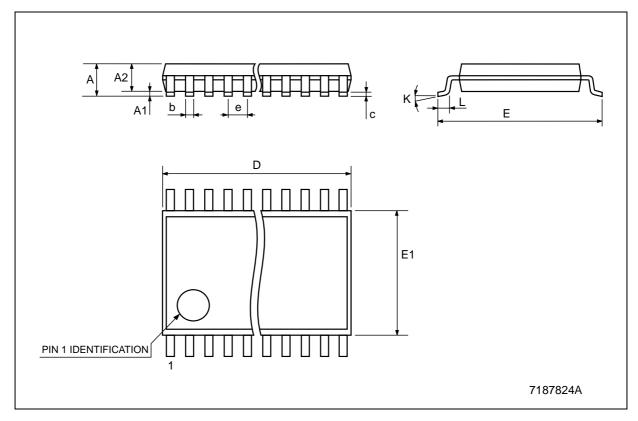


WAVEFORM 4: ENABLE AND DISABLE TIME (A PORT)



TSSOP64 MECHANICAL DATA

DIM.	mm.			inch			
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.	
А			1.1			0.043	
A1	0.05		0.15	0.002		0.006	
A2		0.9			0.035		
b	0.17		0.27	0.0067		0.011	
С	0.09		0.20	0.0035		0.0079	
D	16.9		17.1	0.665		0.673	
E		8.1			0.318		
E1	6.0		6.2	0.236		0.244	
е		0.5 BSC			0.0197 BSC		
К	0°		8°	0°		8°	
L	0.50		0.75	0.020		0.030	



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